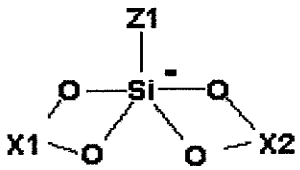
ABSTRACT

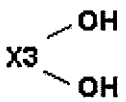
An epoxy resin composition which comprises an epoxy resin (A), a curing agent (B), a curing accelerator (C) and a component retarding curing of the epoxy resin (D) which is at least one component selected from components (a), (b) and (c) represented by general formulae [1], [2] and [3], respectively, a semiconductor device having a semiconductor element encapsulated by using the composition, and a process for providing latency to an epoxy resin composition. The epoxy resin exhibits excellent storage stability, excellent fluidity and curing property during encapsulating by molding and excellent resistance to soldering without forming cleavages or cracks by the soldering treatment at high temperatures in accordance with the lead-free soldering. An epoxy resin composition can be provided with latency by adjusting the amounts of the curing accelerator and the component for retarding curing.

(a) An anion component represented by general formula [1]:



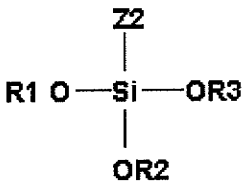
[1]

(b) A compound represented by general formula [2]:



[2]

(c) A silane compound represented by general formula [3]:



[3]